

**COMPLETE TV SOUND CHANNEL**

The TDA3190 is a monolithic integrated circuit in a 16-lead dual in-line plastic package. It performs all the functions needed for the TV sound channel :

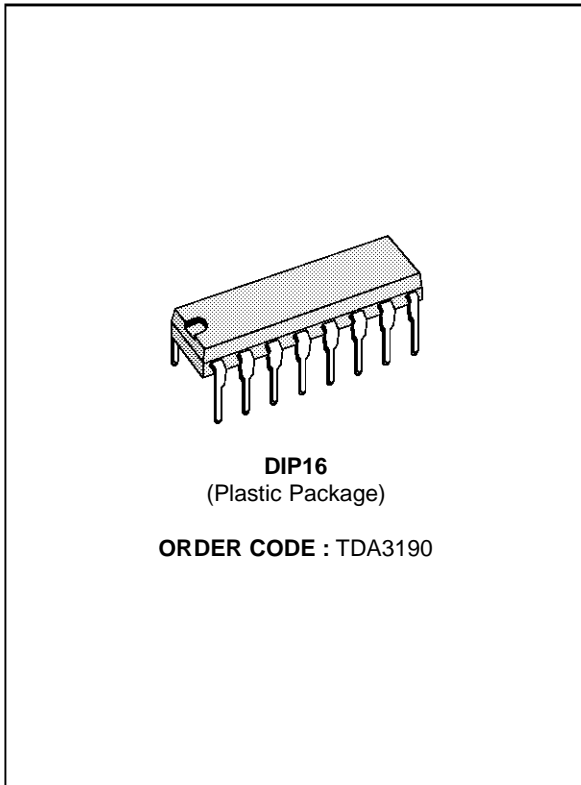
- IF LIMITER AMPLIFIER
- ACTIVE LOW-PASS FILTER
- FM DETECTOR
- DC VOLUME CONTROL
- AF PREAMPLIFIER
- AF OUTPUT STAGE

**DESCRIPTION**

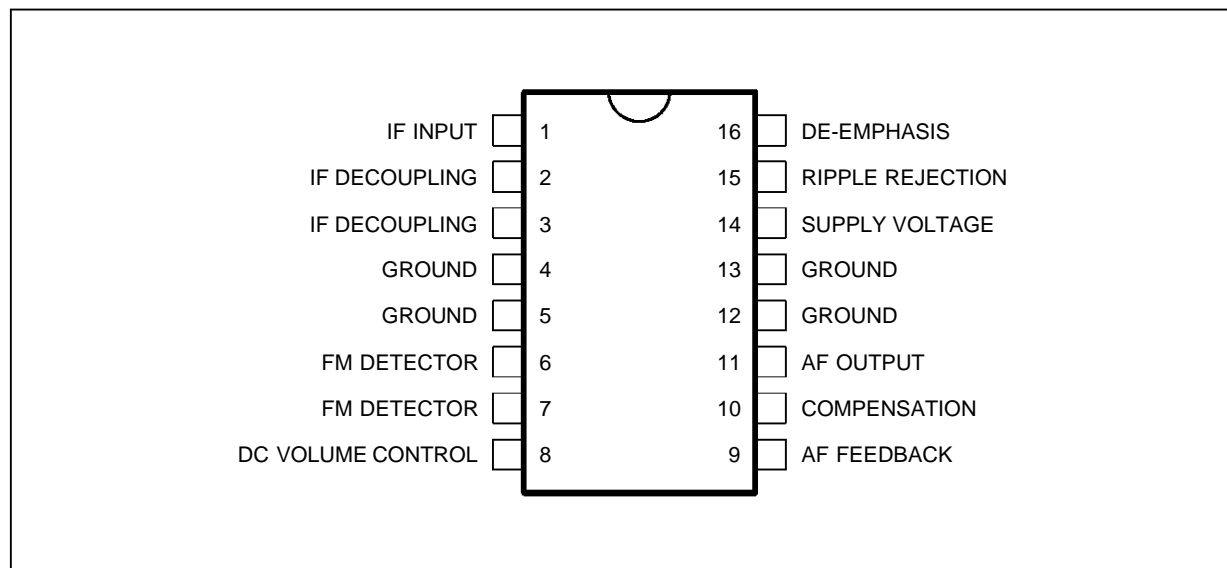
The TDA3190 can give an output power of 4.2 W (d = 10 %) into a 16 Ω load at  $V_S = 24$  V, or 1.5 W (d = 10 %) into an 8 Ω load at  $V_S = 12$  V. This performance, together with the FM-IF section characteristics of high sensitivity, high AM rejection and low distortion, enables the device to be used in almost every type of television receivers.

The device has no irradiation problems, hence no external screening is needed.

The TDA3190 is a pin to pin replacement of TDA1190Z.

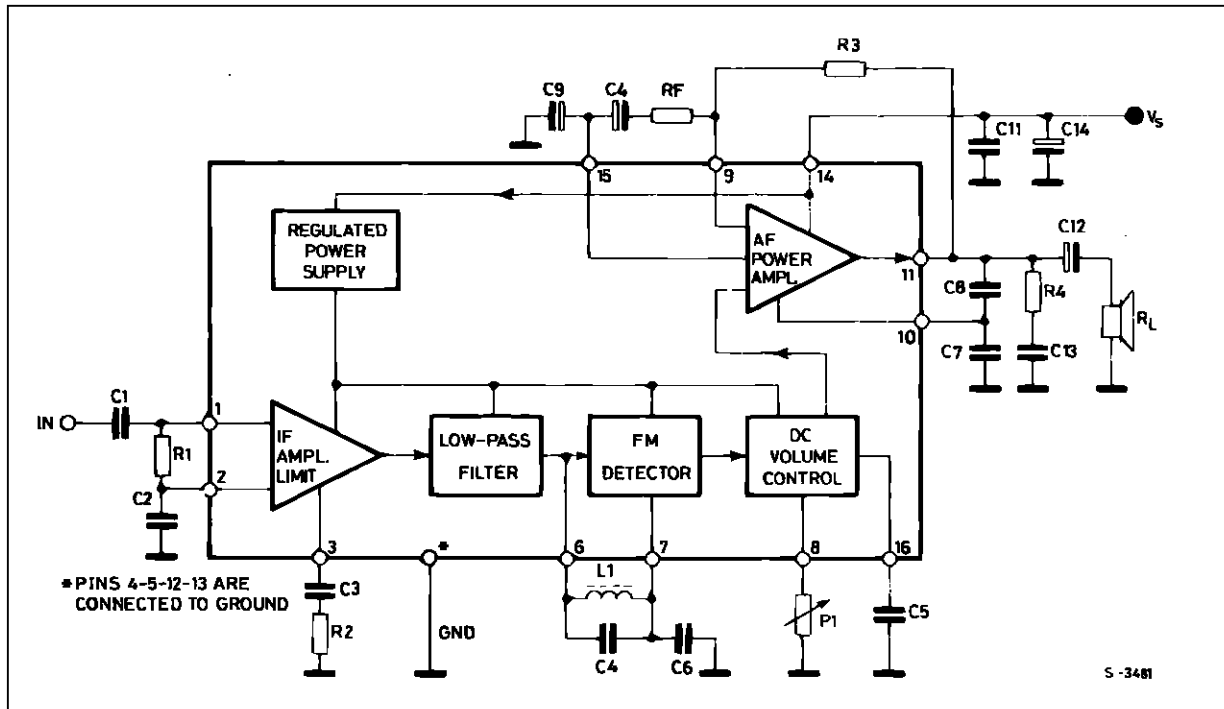


**PIN CONNECTIONS**



3190-01.EPS

BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

| Symbol         | Parameter  | Value       | Unit       |
|----------------|--|-------------|------------|
| $V_s$          | Supply Voltage (pin 10)  | 28          | V          |
| $V_i$          | Input Signal Voltage (pin 1)   | 1           | V          |
| $I_o$          | Output Peak Current (non-repetitive)   | 2           | A          |
| $I_o$          | Output Peak Current (repetitive)   | 1.5         | A          |
| $P_{tot}$      | Power Dissipation at $T_{pins} = 90^\circ C$<br>at $T_{amb} = 70^\circ C$ (free air) | 4.3<br>1    | W<br>W     |
| $T_{stg}, T_j$ | Storage and Junction Temperature   | - 40 to 150 | $^\circ C$ |

THERMAL DATA

| Symbol           | Parameter                           | Value   | Unit         |
|------------------|-------------------------------------|---------|--------------|
| $R_{th\ j-pins}$ | Thermal Resistance Junction-pins    | Max 14  | $^\circ C/W$ |
| $R_{th\ j-amb}$  | Thermal Resistance Junction-ambient | Max 80* | $^\circ C/W$ |

\* Obtained with the GND pins soldered to printed circuit with minimized copper area.

ELECTRICAL CHARACTERISTICS

(refer to the test circuit,  $V_s = 24V$ ,  $T_{amb} = 25^\circ C$  unless otherwise specified)

| Symbol | Parameter                        | Test Conditions                                 | Min.      | Typ.     | Max.      | Unit     |
|--------|----------------------------------|---|-----------|----------|-----------|----------|
| $V_s$  | Supply Voltage (Pin 14)          |   | 9         |          | 28        | V        |
| $V_o$  | Quiescent Output Voltage (Pin11) | $V_s = 24V$<br>$V_s = 12V$                      | 11<br>5.1 | 12<br>6  | 13<br>6.9 | V<br>V   |
| $I_d$  | Quiescent Drain Current          | $P_1 = 22k\Omega$<br>$V_s = 24V$<br>$V_s = 12V$ | 11        | 22<br>19 | 45<br>40  | mA<br>mA |



Figure 1 : Relative Audio Output Voltage and Output Noise versus Input Signal

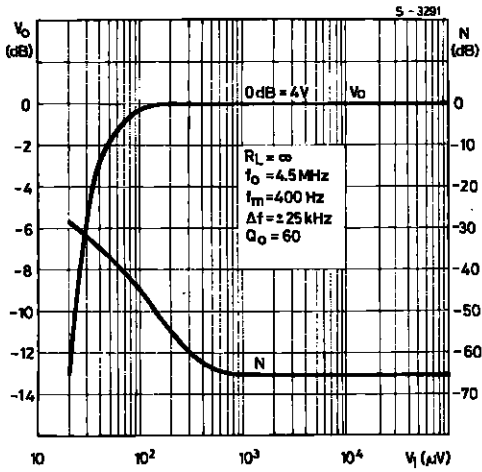


Figure 2 : Output Voltage Attenuation versus DC Volume Control Resistance

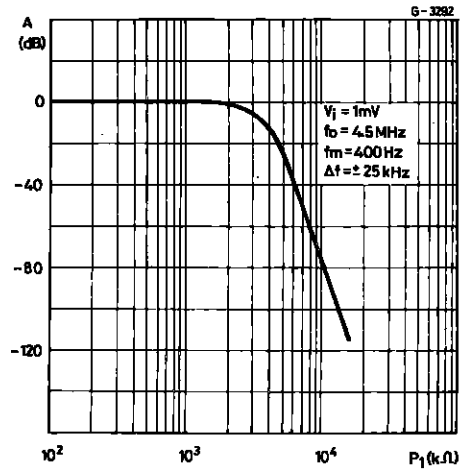


Figure 3 : Amplitude Modulation Rejection versus Input Signal

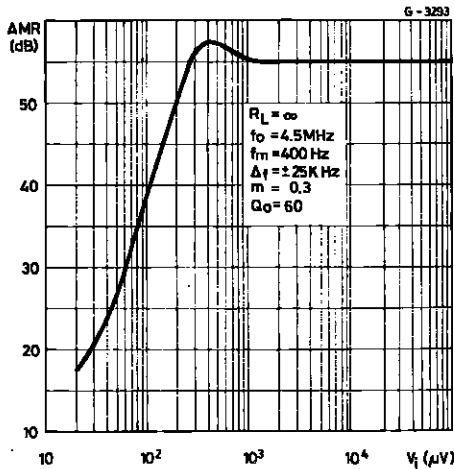


Figure 4 :  $\Delta AMR$  versus Tuning Frequency Change

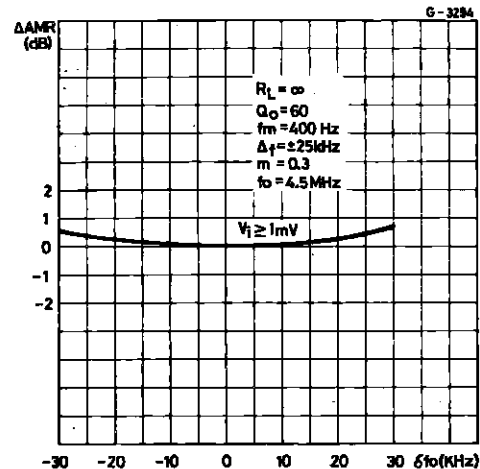


Figure 5 : Recovered Audio Voltage versus Unloaded Q Factor of the Detector Coil

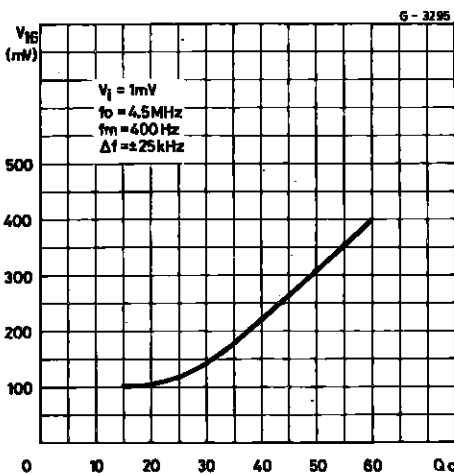
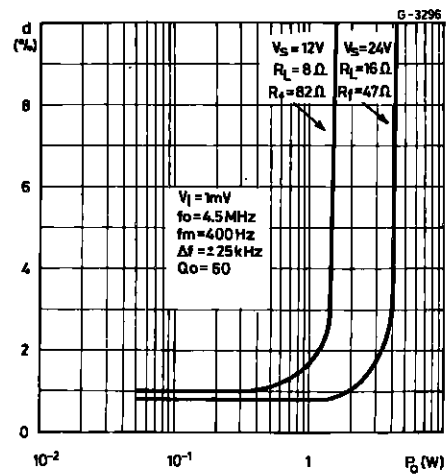
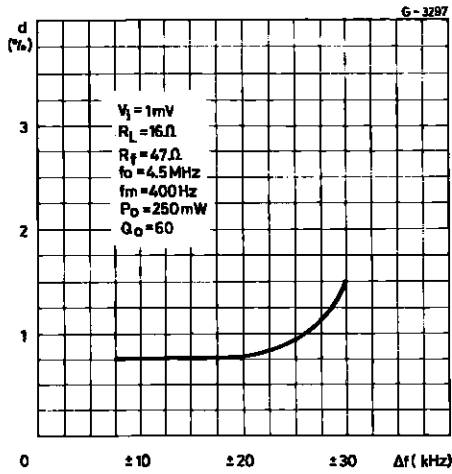


Figure 6 : Distortion versus Output Power

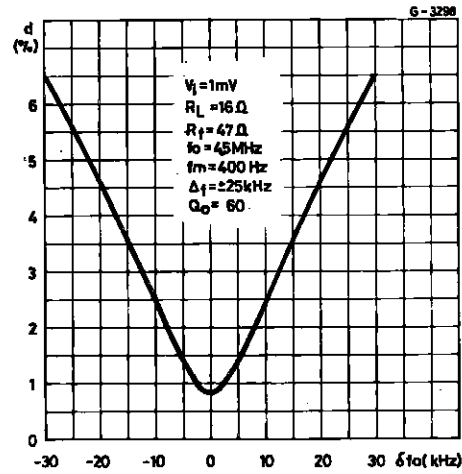


**Figure 7 :** Distortion versus Frequency Deviation



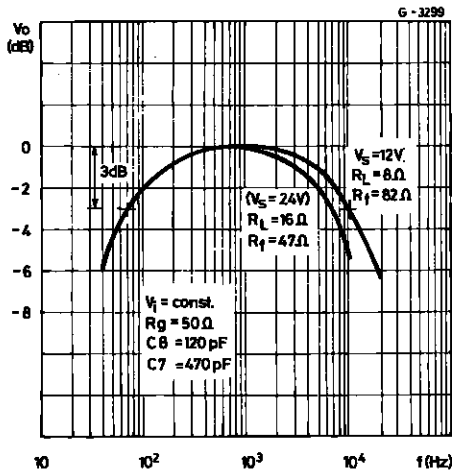
3190-10.EPS

**Figure 8 :** Distortion versus Tuning Frequency Change



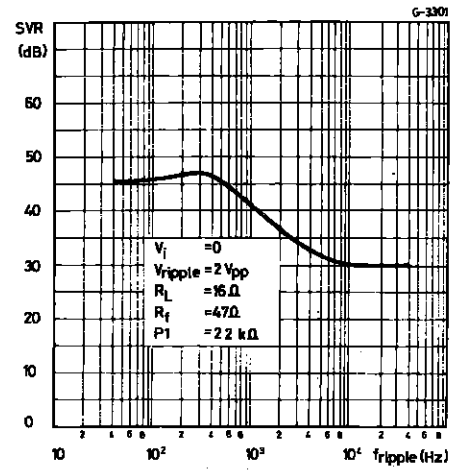
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**Figure 9 :** Audio Amplifier Frequency Response



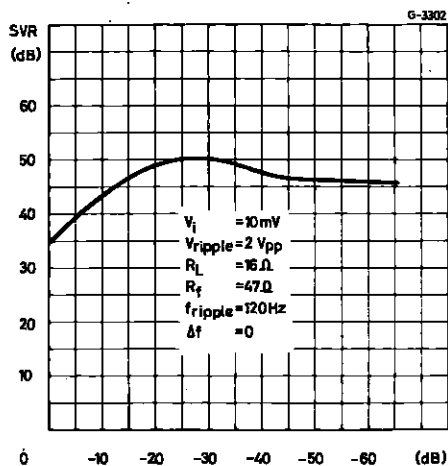
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**Figure 10 :** Supply Voltage Ripple Rejection versus Ripple Frequency



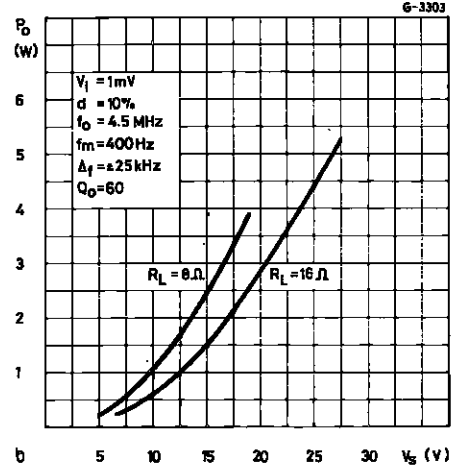
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**Figure 11 :** Supply Voltage Ripple Rejection versus Volume Control Attenuation



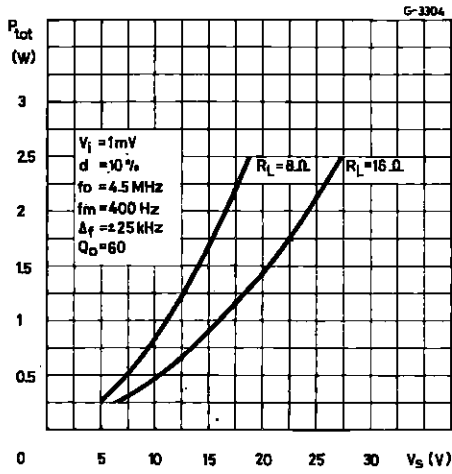
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**Figure 12 :** Output Power versus Supply Voltage



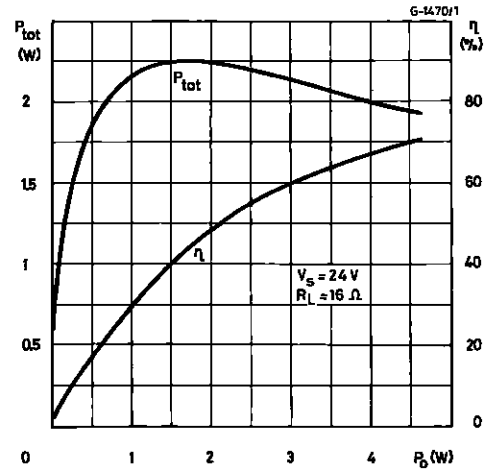
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**Figure 13 :** Maximum Power Dissipation versus Supply Voltage (sinewave operation)



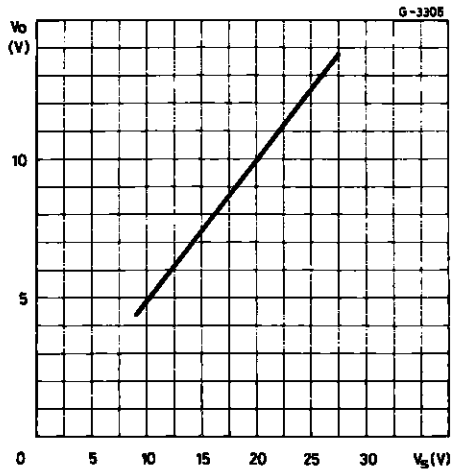
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**Figure 14 :** Power Dissipation and Efficiency versus Output Power



3190-17.EPS

**Figure 15 :** Quiescent Output Voltage (Pin 11) versus Supply Voltage



3190-18.EPS

**APPLICATION INFORMATION**

The electrical characteristics of the TDA3190 remain almost constant over the frequency range 4.5 to 6 MHz, therefore it can be used in all television standards (FM mod.). The TDA3190 has a high input impedance, so it can work with a ceramic filter or with a tuned circuit that provide the necessary input selectivity.

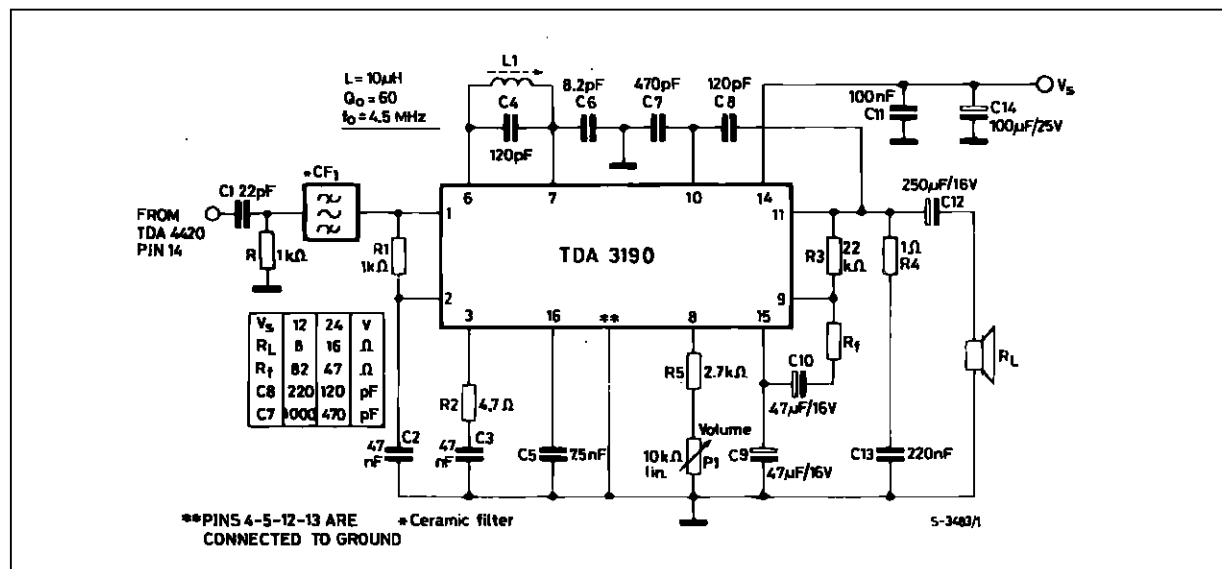
The value of the resistors connected to pin 9, determine the AC gain of the audio frequency amplifier. This enables the desired gain to be selected in relation to the frequency deviation at which the output stage of the AF amplifier, must enter into

clipping.

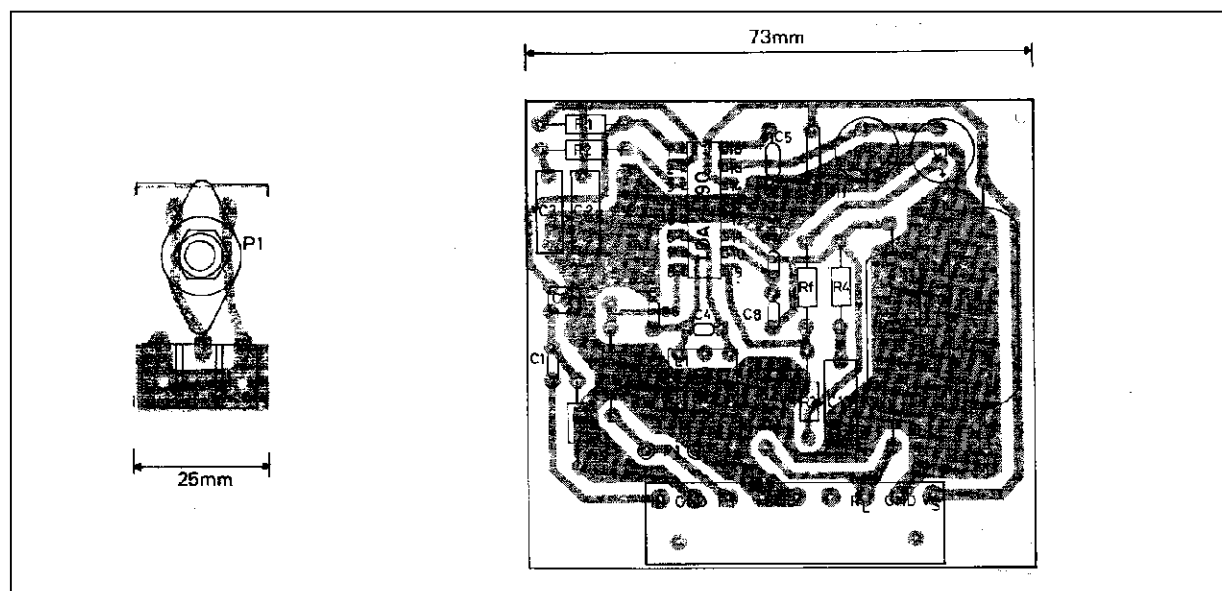
Capacitor C8, connected between pins 10 and 11, determines the upper cutoff frequency of the audio bandwidth. To increase the bandwidth the values of C8 and C7 must be reduced, keeping the ratio C7/C8 as shown in the table of fig. 16.

The capacitor connected between pin 16 and ground, together with the internal resistor of 10 KΩ forms the de-emphasis network. The Boucherot cell eliminates the high frequency oscillations caused by the inductive load and the wires connecting the loudspeaker.

**Figure 16 :** Typical Application Circuit



**Figure 17 :** P.C. Board and Component Layout of the Circuit shown in Figure 16 (1 : 1 scale)

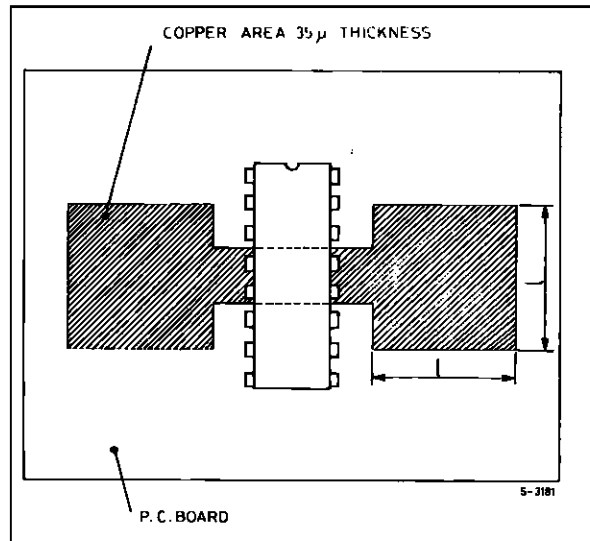


**MOUNTING INSTRUCTION**

The  $R_{th\ j-amb}$  of the TDA3190 can be reduced by soldering the GND pins to a suitable copper area of the printed circuit board (fig. 18) or to an external heatsink (fig. 19).

The diagram of figure 20 shows the maximum dissipable power  $P_{tot}$  and the  $R_{th\ j-amb}$  as a function of the side "l" of two equal square copper areas

**Figure 18 :** Example of P.C. Board Copper Area which is used as Heatsink



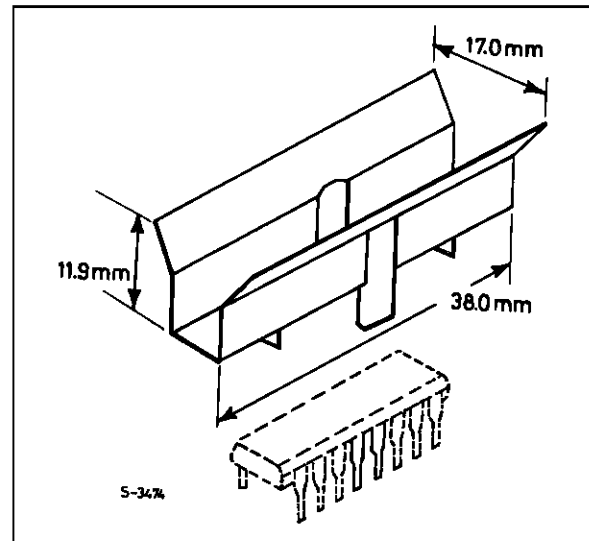
3190-21.EPS

having a thickness of  $35\ \mu$  (1.4 mils).

During soldering the pins temperature must not exceed  $260\ ^\circ\text{C}$  and the soldering time must not be longer than 12 seconds.

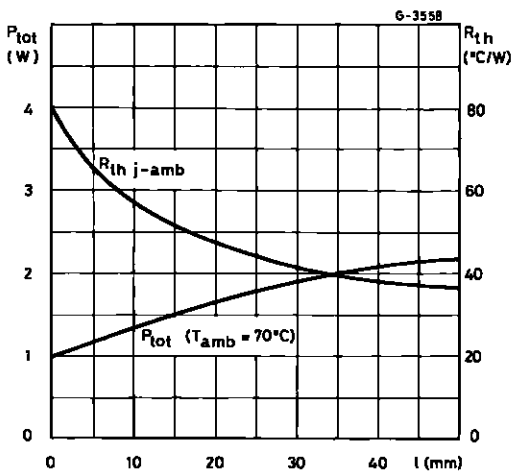
The external heatsink or printed circuit copper area must be connected to electrical ground.

**Figure 19 :** External Heatsink Mounting Example



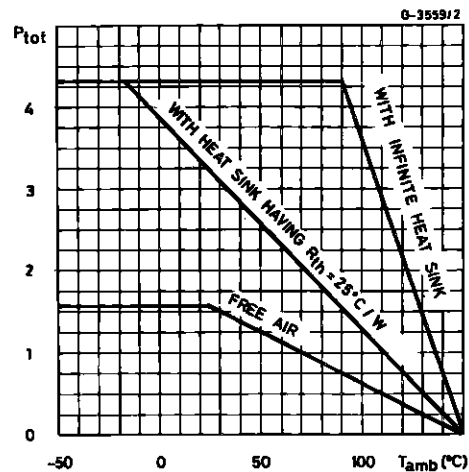
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**Figure 20 :** Maximum Dissippable Power and Junction to Ambient Thermal Resistance versus Side "T"



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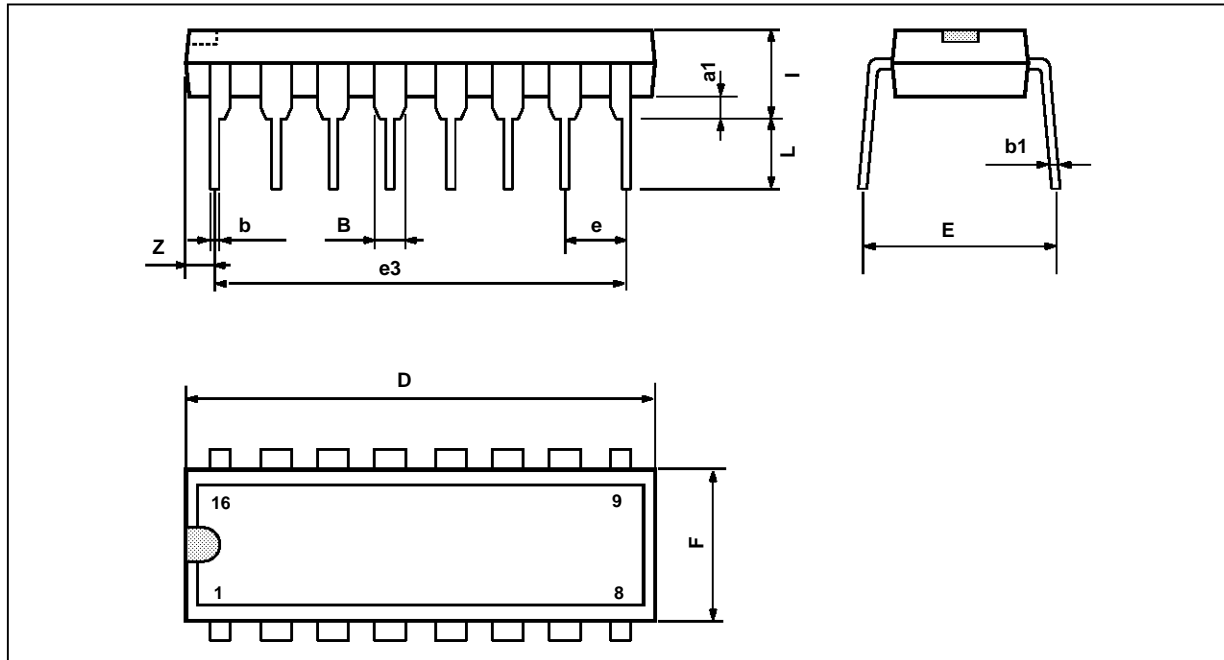
**Figure 21 :** Maximum Allowable Power Dissipation versus Ambient Temperature



3190-24.EPS



**PACKAGE MECHANICAL DATA**  
16 PINS - PLASTIC DIP



PM-DIP16.EPS

| Dimensions | Millimeters |       |      | Inches |       |       |
|------------|-------------|-------|------|--------|-------|-------|
|            | Min.        | Typ.  | Max. | Min.   | Typ.  | Max.  |
| a1         | 0.51        |       |      | 0.020  |       |       |
| B          | 0.77        |       | 1.65 | 0.030  |       | 0.065 |
| b          |             | 0.5   |      |        | 0.020 |       |
| b1         |             | 0.25  |      |        | 0.010 |       |
| D          |             |       | 20   |        |       | 0.787 |
| E          |             | 8.5   |      |        | 0.335 |       |
| e          |             | 2.54  |      |        | 0.100 |       |
| e3         |             | 17.78 |      |        | 0.700 |       |
| F          |             |       | 7.1  |        |       | 0.280 |
| i          |             |       | 5.1  |        |       | 0.201 |
| L          |             | 3.3   |      |        | 0.130 |       |
| Z          |             |       | 1.27 |        |       | 0.050 |

DIP16.TBL

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